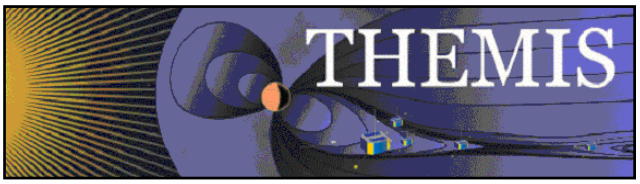

THEMIS
Probe-to-SCM Mag Boom
Interface Control Document (ICD)

thm_sys_113AD_SCB_ICD.doc
Version: AD
Release: 11 March 2005

Written by : Bill Donakowski/Christopher Smith/Tien Fak Tan
U.C. Berkeley THEMIS Mechanical Engineering

_____

Ellen Taylor, U.C.Berkeley THEMIS Mission Systems Engineer

_____

Paul Turin, U.C.Berkeley THEMIS Mechanical Systems Engineer

_____

Kevin Brenneman, Swales Aerospace, THEMIS Spacecraft Systems Engineer

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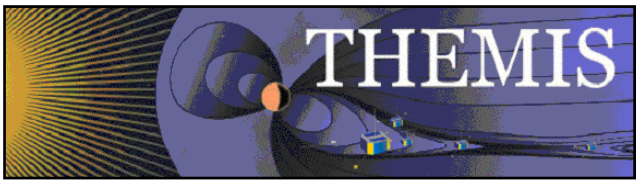
Rob Eppler, U.C.Berkeley THEMIS Spacecraft Mechanical Engineer

_____

Peter Harvey, U.C.Berkeley THEMIS Project Manager



Document Revision Record

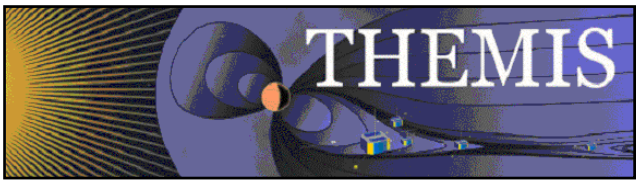
Rev.	Date	Description of Change	Approved By
D1	15 SEP 2003	Preliminary Draft	-
D2	13 OCT 2003	Second Draft: Addition of detailed temperature limits to Preliminary Draft. Updated mass numbers to meet SRR numbers.	
-	31 MAR 2004	Final Release: Updated per ICD drawings. Updated Thermal Sections.	
AA	25 MAY 2004	Baseline: Updated per Swales comments Appended Mechanical ICD Drawings	
AB	04 OCT 2004	Updated Mechanical ICD Drawing	
AC	05 NOV 2004	Updated Mechanical ICD Drawing	
AD	11 MAR 2005	Removed thermal information which has been relocated to the THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD	

Drawing Revision Record

Rev.	Date	Description of Change	Approved By
AA	5/25/04	THM-SCB-ICD-001 Baseline Release	
AB	8/9/04	THM-SCB-ICD-001 Rev AB	
AC	10/24/04	THM-SCB-ICD-001 Rev AC	
AD	03/11/05	Updated and improved thermal information Signature Page: Updated the Swales Systems Lead	

Distribution List

Name	Email
Peter Harvey, Project Manager, U.C.Berkeley	prh@ssl.berkeley.edu;
Paul Turin, Mechanical Lead, U.C.Berkeley	pturin@ssl.berkeley.edu;
Chris Smith, Thermal Lead, UC Berkeley	csmith@ssl.berkeley.edu;
Ellen Taylor, Mission Systems, U.C.Berkeley	ertaylor@ssl.berkeley.edu;
Tien Fak Tan, Mag Boom Mech Lead, U.C.Berkeley	ttan@me.berkeley.edu;
Tom Ajluni, Spacecraft Systems, Swales Aerospace	tajluni@swales.com;
Bob Kraeuter, Electrical Systems, Swales Aerospace	rkraeuter@swales.com;
Richard LeBoeuf, ACS Lead, Swales Aerospace	rleboeuf@swales.com;



Rommel Zara, Thermal Lead, Swales Aerospace	rzara@swales.com;
Kevin Brenneman, Spacecraft Systems, Swales Aerospace	kbrenneman@swales.com;
Mike Cully, Probe Project Manager, Swales Aerospace	mcully@swales.com;
Rob Eppler, Mechanical Systems, Swales Aerospace	weppler@swales.com;
Chris Lashley, Mechanical Systems, Swales Aerospace	clashley@swales.com;
Warren Chen, Spacecraft Systems, Swales Aerospace	wchen@swales.com

TBD List

Identifier	Description

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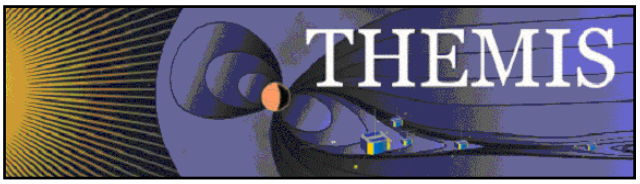


1. Introduction

This document shall describe the interface between the THEMIS probe bus and the SCM-Mag Booms. Each THEMIS probe shall carry one SCM-Mag Boom.

1.1 Scope

This Interface Control Document (ICD) will define the flight hardware interface requirements, mechanical and thermal model requirements, data/information deliverables, GSE/Developmental unit requirements, and Verification Matrix with Verification requirements. Functional/Performance requirements are found in the requirements database, and Environmental requirements are found in the Verification Plan and Environmental Specification.

1.2 Component Description

The SCM-Mag Boom suspends the Search Coil Magnetometer (SCM) at a distance of about 1 meter from the THEMIS probe. The SCM-Mag Boom is connected to the probe at the top deck and when deployed is in a position 180 degrees from the FGM-Mag Boom.

1.3 Document Conventions

In this document, TBD (To Be Determined) means that no data currently exists. A value followed by TBR (To Be Resolved) means that this value is preliminary. In either case, the value is typically followed by UCB (University of California at Berkeley) and / or SA (Swales Aerospace) indicating who is responsible for providing the data, and a unique reference number.

1.4 Applicable Documents

The following documents include drawings and THEMIS Project policies, and are part of the Interface Requirements. In the event of a conflict between this ICD and the following documents, this ICD takes precedence. All ICD documents and drawings can be found on the Berkeley THEMIS FTP site:
ftp://apollo.ssl.berkeley.edu/pub/THEMIS/

1. THEMIS SCM Instrument Assembly Drawing, File THM-SCB-ICD-001
2. THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD

The following documents are government documents, provided as references for the Interface Requirements.

1. EWR-127-1: Eastern and Western Range Safety Requirements
2. MIL-HDBK-340A: Application Guidelines for MIL-STD-1540; Test Requirements for Launch, Upper Stage, and Space Vehicles

3. MIL-STD-1522A: Standard General Requirements for Safe Design and Operation of Pressurized Missile and Space Systems
4. MIL-STD-1540D: Product Verification Requirements for Launch, Upper-stage, and Space Vehicles
5. NPG 6000.1E: Requirements for Packaging, Handling and Transportation for Aeronautical and Space Systems, Equipment, and Associated Components, dated April 26, 1999

1.5 Units

The drawings contained in this document are dual dimensioned, inches (mm).

2. Mechanical Interface

2.1 Interface Drawing

The mechanical configuration of the SCM Instrument is shown in the SCM Interface Drawing THM-SCB-ICD-001. These include a dimensioned drawing detailing envelope, mounting, and connector locations, CG location, coordinates, thermal surface finishes, and thermal interface reference.

2.1.1 Instrument Envelopes

The envelope specified is the static envelope, inclusive all instrument hardware and blankets. The actual flight instrument as delivered to Swales is to be within this envelope. Dynamic deflections of the instrument in Launch Mode will be accounted for by Swales as long as the instrument minimum frequency requirement is met. The SCM-Mag Boom instrument and overall envelope geometry and dimensions are as shown in THM-SCB-ICD-001.

2.1.1.1 Instrument Stowed Envelope

The Instrument Interface Drawing, THM-SCB-ICD-001 is the controlling reference that specifies the Launch mode mechanical interface.

2.1.1.2 Instrument Deployed Envelope

The Instrument interface drawing, THM-SCB-ICD-001 is the controlling reference that specifies the On-Orbit mode mechanical interfaces:

2.2 Coordinate Systems

The instrument coordinate system relative to the instrument interface is shown in the Instrument Interface Drawing**,** THM-SCB-ICD-001. All instrument information is defined relative to this Instrument coordinate system.

2.3 Field of View

2.3.1 Field of View

The Instrument Interface Drawing THM-SCB-ICD-001 is the controlling reference that specifies the On-Orbit mode Fields of View.

2.3.2 Field of Travel

The Instrument Interface Drawing THM-SCB-ICD-001 is the controlling reference that specifies the On-Orbit mode Fields of Travel.

2.4 Mass Properties

The mass of the SCM Boom shall be measured prior to delivery to within $\pm$0.01kg. The Center of Gravity (CG), as documented in THM-SCB-ICD-001 and referenced to the instrument coordinate axes described above, shall be predicted through analysis. The stowed and deployed Moments of Inertia (MOIs) of the SCM Boom, as documented in THM-SCB-ICD-001 and referenced to the Instrument coordinate axes described above, shall be predicted through analysis.

2.5 Mounting

2.5.1 Mounting Method

The SCM-Mag Boom shall be mounted to the top deck of the S/C though the base bracket, which fixes the instrument to the probe, and frangibolt housing, which keeps the instrument stowed during launch. The bolt pattern for the base bracket consists of 5 Bolts and Washers on a single interface plane and is described in the instrument interface drawing THM-SCB-ICD-001. The bolt pattern for the frangibolt housing consists of 4 Bolts and Washers on a single interface plane and is described in the instrument interface drawing THM-SCB-ICD-001. An additional component, the SCM pre-amp box, will be mounted on the IDPU. All Bolts to be 8-32 UNC sized. Connection is bolted only; no pinning or other hardware is required. Built in flexures in the mounting feet provide semi-kinematic mounting to accommodate differential expansion across the interface.

2.5.2 Mounting Interface

Mounting hole coordinates, dimensions, orientation, and tolerances are shown in the Instrument Interface Drawing**,** THM-SCB-ICD-001. Mounting hole tolerances shall be dimensioned in accordance with ANSI Standard Y14.5M, "Dimensioning and Tolerancing", 1999 or later revisions.

2.5.3 Mounting Hardware

All fasteners shall be provided by Swales. Swales shall provide all shims as required to meet alignment requirements.

2.5.4 Mounting Surface Requirements

2.5.4.1 Flatness

The mounting surface of the instrument shall be fabricated to a flatness tolerance of 0.005 inches or less to ensure the required electrical and thermal contacts as well as the required alignment accuracy. The Probe Bus mounting surface shall be flat to the tolerance 0.005 inches or less. Instrument mounting surface characteristics shall be documented in the instrument interface drawing THM-SCB-ICD-001.

2.5.4.2 Surface Finish

The mounting surface of the instrument shall be fabricated to a surface finish of 32 micro-inches RMS or less to ensure the required electrical and thermal contacts as well as the required alignment accuracy.

2.5.5 Mounting Location

The instrument origin location is documented in THM-SCB-ICD-001.

2.5.6 Drill Templates

A drill template will be provided by UCB to swales to verify the bolt patterns and the relative position of multiple sets of bolt patterns.

2.5.7 Spacecraft Mounting

2.5.7.1 Orientation During Integration

Instruments shall be capable of being installed/removed with the Probe Bus X/Y axes horizontal.

2.5.7.2 Mounting Impacts

The Instrument Components shall be capable of being installed or removed during ground operations without degradation, damage or disqualification of the flight hardware.

2.6 Alignment.

2.6.1 Alignment Responsibilities

Swales is responsible for aligning the instrument to the bus. The Instrument is responsible for aligning the sensing elements to the interface plate.

2.6.2 Alignment Requirements

The instrument shall be placed relative to the bus coordinate system within the tolerances shown in THM-SCB-ICD-001. The Alignment method shall be bolt-hole tolerances.

2.7 Mechanisms

The SCM-Mag Booms are deployed when frangibolts are activated.

2.8 Access To Instrument

2.8.1 General Access

All items to be installed, removed, or replaced at the Probe Bus/Carrier level shall be accessible without disassembly of the item.

2.8.2 Specific Access

The following table provides a list of test connectors, contamination covers, and any other I&T equipment that must be installed or removed during integration, environmental test or at the launch site.

Table 2.8.2: Access Requirements

Item	Last Access	Function
MAG Boom Restraint	Launch Site prior to Probe Carrier Assembly Integration	Provides safety guard for inadvertent mag boom deploy
MAG Boom Simulator	Swales: Instrument Integration	Provides electrical test of boom deploy

Test Items: All items to be removed prior to test shall be tagged with a red tag stating, "REMOVE BEFORE TEST". All items to be installed prior to test shall be tagged with a green tag.

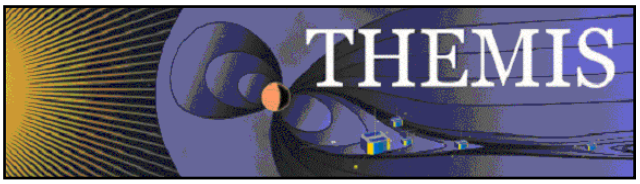
Flight Items: All items to be removed prior to flight shall be tagged with a red tag stating, "REMOVE BEFORE FLIGHT". All items to be installed prior to flight shall be tagged with a green tag.

2.8.3 Mechanical Test Instrumentation Access

The Instrument shall accommodate mounting area and access to temporarily installed acceleration sensors and supporting hardware for purposes of monitoring accelerations during Instrument, Probe Bus, and Probe Carrier Assembly ground test..

3. Thermal Interface

Thermal interface information has been transferred to Ref 11 THEMIS Instrument Thermal Specification, THM_SYS_119_ITH_ICD



3.1 Thermal Design

This section has been moved to Reference 11.

3.2 Thermal Design & Analysis Responsibilities

This section has been moved to Reference 11.

3.3 Heat Transfer

This section has been moved to Reference 11.

3.4 Power Dissipation

The nominal and maximum power dissipation is provided in THM_SYS_009. Power levels used in thermal modeling are given in Reference 11

3.5 Temperature Requirements

This section has been moved to Reference 11.

3.6 Temperature Monitoring and Control

This section has been moved to Reference 11.

3.7 Contamination Control

This section has been moved to Reference 11.